

Inventor: Shozo Nagano et al.

Title: Conductive Integrated Circuit Metal Alloy Interconnections, Electroplating Anodes, Metal Alloys For Use As a Conductive Interconnection In An Integrated Circuit, And Physical Vapor Deposition Targets

Assignee: Micron Technology, Inc.

SAH
#3
7-6-01

JC868 U.S. PTO
09/784234
02/14/01

INFORMATION DISCLOSURE STATEMENT

PURSUANT TO 37 C.F.R. §§ 1.56, 1.97 AND 1.98

In compliance with 37 C.F.R. §§ 1.56, 1.97 and 1.98, your attention is directed to the United States patents and other references listed on the attached Form PTO-1449. No admission is made regarding whether all the submitted references are prior art.

The listed references were cited by, or submitted to, the Office in the parent, co-pending application of the above-identified application. The above-identified application is a divisional application of co-pending application Serial No. 09/449,025, filed November 4, 1999. Such prior disclosure is sufficient for the above-identified application as far as copies of the references are concerned. 37 C.F.R. § 1.98(d) and MPEP § 609(2).

Citation of these references is respectfully requested.

Respectfully submitted,

Dated: 2-13-01

By: Mark S. Matkin

Mark S. Matkin
Reg. No. 32,268